

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10557694
<b>Filing Date:</b>	22-Nov-2005
<b>Title of Invention:</b>	Resin for photoresist composition, photoresist composition and method for forming resist pattern
<b>First Named Inventor/Applicant Name:</b>	Hideo Hada
<b>Filer:</b>	Neil S. Bartfeld
<b>Attorney Docket Number:</b>	SHIGA7.033APC

Filed as Large Entity

### **U.S. National Stage under 35 USC 371 Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
-------------	----------	----------	--------	----------------------

**Basic Filing:**

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

**Post-Allowance-and-Post-Issuance:**

**Extension-of-Time:**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Submission- Information Disclosure Stmt	1806	1	180	180
<b>Total in USD (\$)</b>				<b>180</b>